

E1SBA12-25.001875M

[Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on May 26, 2020)


[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



ITEM DESCRIPTION

Quartz Crystal Resonator HC49/UP Short 2 Pad Surface Mount (SMD) 3.2mm Height Metal Resistance Weld Seal 25.001875MHz ± 50 ppm at 25°C, ± 100 ppm over -20°C to +70°C 12pF Parallel Resonant

ELECTRICAL SPECIFICATIONS

| | |
|-------------------------------|---|
| Nominal Frequency | 25.001875MHz |
| Frequency Tolerance/Stability | ± 50 ppm at 25°C, ± 100 ppm over -20°C to +70°C |
| Aging at 25°C | ± 5 ppm/year Maximum |
| Load Capacitance | 12pF Parallel Resonant |
| Shunt Capacitance | 7pF Maximum |
| Equivalent Series Resistance | 40 Ohms Maximum |
| Mode of Operation | AT-Cut Fundamental |
| Drive Level | 1mWatt Maximum |
| Storage Temperature Range | -55°C to +125°C |
| Insulation Resistance | 500 Megaohms Minimum (Measured at 100Vdc) |

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| | |
|------------------------------|---|
| ESD Susceptibility | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A |
| Flammability | UL94-V0 |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Mechanical Shock | MIL-STD-202, Method 213, Condition C |
| Moisture Resistance | MIL-STD-883, Method 1004 |
| Moisture Sensitivity | J-STD-020, MSL1 |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B |
| Vibration | MIL-STD-883, Method 2007, Condition A |

E1SBA12-25.001875M [Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)



| LINE | MARKING |
|------|--|
| 1 | E25.001M E=Ecliptek Designator |

Suggested Solder Pad Layout

All Dimensions in Millimeters

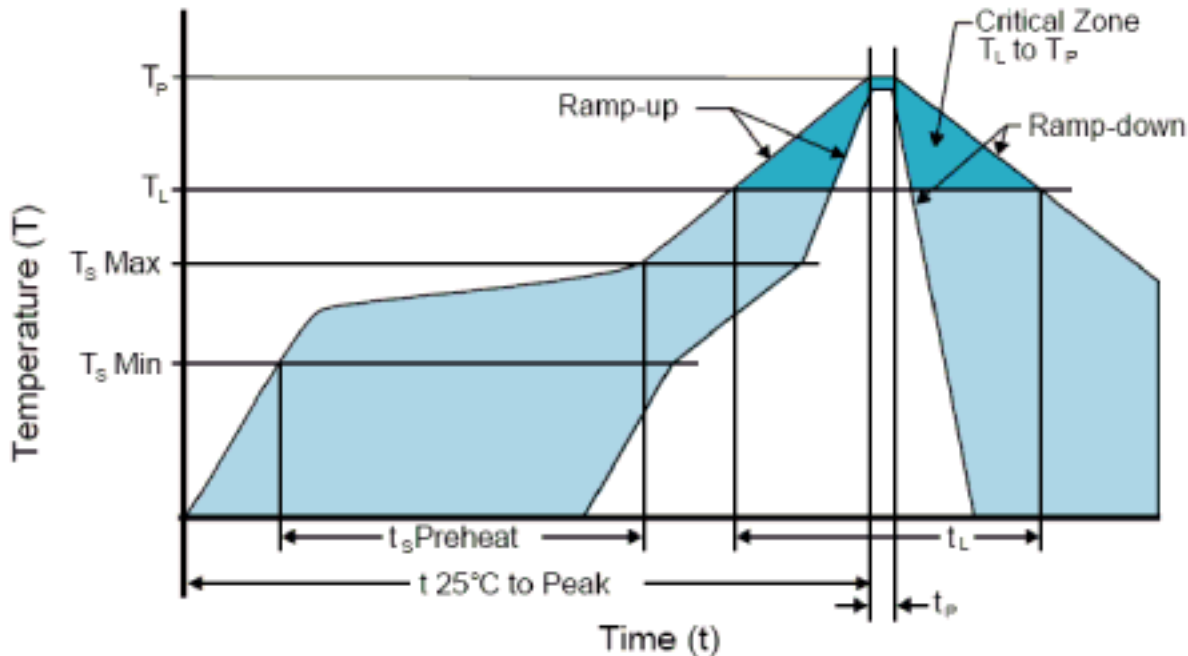


All Tolerances are ±0.1

E1SBA12-25.001875M

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

| | |
|--|---|
| Ts MAX to TL (Ramp-up Rate) | 3°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (Ts MIN) | 150°C |
| - Temperature Typical (Ts TYP) | 175°C |
| - Temperature Maximum (Ts MAX) | 200°C |
| - Time (ts MIN) | 60 - 180 Seconds |
| Ramp-up Rate (TL to TP) | 3°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (TL) | 217°C |
| - Time (tL) | 60 - 150 Seconds |
| Peak Temperature (TP) | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (TP Target) | 250°C +0/-5°C |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds |
| Ramp-down Rate | 6°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | 8 Minutes Maximum |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

E1SBA12-25.001875M

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

| | |
|--|--|
| Ts MAX to TL (Ramp-up Rate) | 5°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (Ts MIN) | N/A |
| - Temperature Typical (Ts TYP) | 150°C |
| - Temperature Maximum (Ts MAX) | N/A |
| - Time (ts MIN) | 30 - 60 Seconds |
| Ramp-up Rate (TL to TP) | 5°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (TL) | 150°C |
| - Time (tL) | 200 Seconds Maximum |
| Peak Temperature (TP) | 245°C Maximum |
| Target Peak Temperature (TP Target) | 245°C Maximum 2 Times / 230°C Maximum 1 Time |
| Time within 5°C of actual peak (tp) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| Ramp-down Rate | 5°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)